

Radiation-Hardened Electronics for Space Application Market, Global Outlook and Forecast 2022-2028

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Abstracts

This report contains market size and forecasts of Radiation-Hardened Electronics for Space Application in Global, including the following market information:

Global Radiation-Hardened Electronics for Space Application Market Size 2023-2028, (\$ millions)

The global Radiation-Hardened Electronics for Space Application market is projected to reach US\$ million by 2028.

MARKET MONITOR GLOBAL, INC (MMG) has surveyed the Radiation-Hardened Electronics for Space Application companies, and industry experts on this industry, involving the revenue, demand, product type, recent developments and plans, industry trends, drivers, challenges, obstacles, and potential risks.

Total Market by Segment:

Global Radiation-Hardened Electronics for Space Application Market, by Type, 2023-2028 (\$ millions)

Global Radiation-Hardened Electronics for Space Application Market Segment Percentages, by Type

Silicon Material

Gallium Nitride Material



Silicon Carbide Material

Others

Global Radiation-Hardened Electronics for Space Application Market, by Application, 2023-2028 (\$ millions)

Global Radiation-Hardened Electronics for Space Application Market Segment Percentages, by Application

Satellite

Launch Vehicle

Deep Space Probe

Others

Global Radiation-Hardened Electronics for Space Application Market, By Region and Country, 2023-2028 (\$ Millions)

Global Radiation-Hardened Electronics for Space Application Market Segment Percentages, By Region and Country

> United States Europe Asia China

Rest of World

Competitor Analysis



The report also provides analysis of leading market participants including:

Further, the report presents profiles of competitors in the market, key players include:

3D Plus

Analog Devices, Inc.

Apogee Semiconductor

Cobham Plc

Data Device Corporation

Exxelia

General Dynamics

GSI Technology, Inc.

Infineon Technologies

Mercury Systems, Inc.

Microchip Technology, Inc.

Micropac Industries

Renesas Electronics Corporation

Solid State Devices, Inc.

STMicroelectronics N.V.

Teledyne Technologies

Texas Instruments

Vorago Technologies



Xilinx, Inc.



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